Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A0609-01** DATE: **9/29/2006**

Product Affected: 655L, 24.5x19.5mm FCBGA
(See attached affected part # list)

Date Effective: **12/29/2006**

MEANS OF DISTINGUISHING CHANGED DEVICES:

☐ Product Mark
☐ Back Mark
☐ Date Code
☒ Other Lot # will have "SP" prefix

Contact: Bimla Paul
Title: Product Quality Assurance
Phone #: (408) 574-6419
Fax #: (408) 284-8362
E-mail: Bimla.Paul@idt.com

Attachment: ☒ Yes ☐ No

Samples: Please contact your local sales representative for sample request & availability.

DESCRIPTION AND PURPOSE OF CHANGE:

☐ Die Technology
☐ Wafer Fabrication Process
☐ Assembly Process
☐ Equipment
☐ Material
☐ Testing
☒ Manufacturing Site
☐ Data Sheet
☐ Other

This notification is to advise our customers that IDT has added SPIL, Taiwan as an alternate Assembly facility for 655L, 24.5x19.5mm FCBGA package. There is no change to the moisture performance of the package as a result of this change.

Please see attached for the qualification data and affected part number list.

RELIABILITY/QUALIFICATION SUMMARY:

Please refer to the attached Qualification & Reliability data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer:

☐ ***Approval for shipments prior to effective date.***

Name/Date:

E-Mail Address:

Title:

Phone# /Fax# :

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY:

DATE:

ATTACHMENT I - PCN # : A0609-01

PCN Type: Manufacturing Site - Alternate Assembly Location

Data Sheet Change: None

No change in moisture sensitivity level (MSL)

Detail Of Change:

This notification is to advise our customers that IDT has added SPIL, Taiwan as an alternate Assembly facility for 655L, 24.5x19.5mm FCBGA package. The assembly material set for SPIL assembly location is listed in Table 1.

There is no change in the moisture sensitivity level (MSL) as a result of this change.

Attachment I outlines the qualification data and affected part#s.

Table 1

Description	Existing	Add
Assembly Location	AMKOR Philippines, Korea and Taiwan, STATSChipPAC, Korea	SPIL, Taiwan
Assembly Material	95Pb/5Sn (High Pb Bump), NAU6 or CRP-4152RA (Underfill), TTG3 (Thermal Grease), 96.5Sn/3Ag/0.5Cu (Solder Ball)	95Pb/5Sn (High Pb Bump), U8439-1 (Underfill), TTG3 (Thermal Grease), 96.5Sn/3Ag/0.5Cu (Solder Ball)

Sample Availability:

Samples are already available for customer evaluation.
Please contact your local IDT sales representative for your sample request and availability.

ATTACHMENT I - PCN # : A0609-01

Qualification Information and Qualification Tests Result:

Test Vehicles: 31 x31 mm FCBGA, 740 balls (1 assembly lot)

Test Description	Test Method	Test Results (SS/ Rej)
* Temperature Cycling (-40°C to +125°C, 1000 cycles)	JESD22-A104	45/0
* HAST (110°C / 85% RH, 264 hours)	JESD22-A110	45/0
High Temperature Stabilization Bake (150 °C, 1000 hours)	JESD22-A103	45/0
Moisture Sensitivity Classification, L4	J-STD-020	90/0

Notes: * Test requires moisture pre-conditioning sequence per JESD22-A113.

Affected Part #s

IDTAMB0480A5RH
IDTAMB0480A5RJ